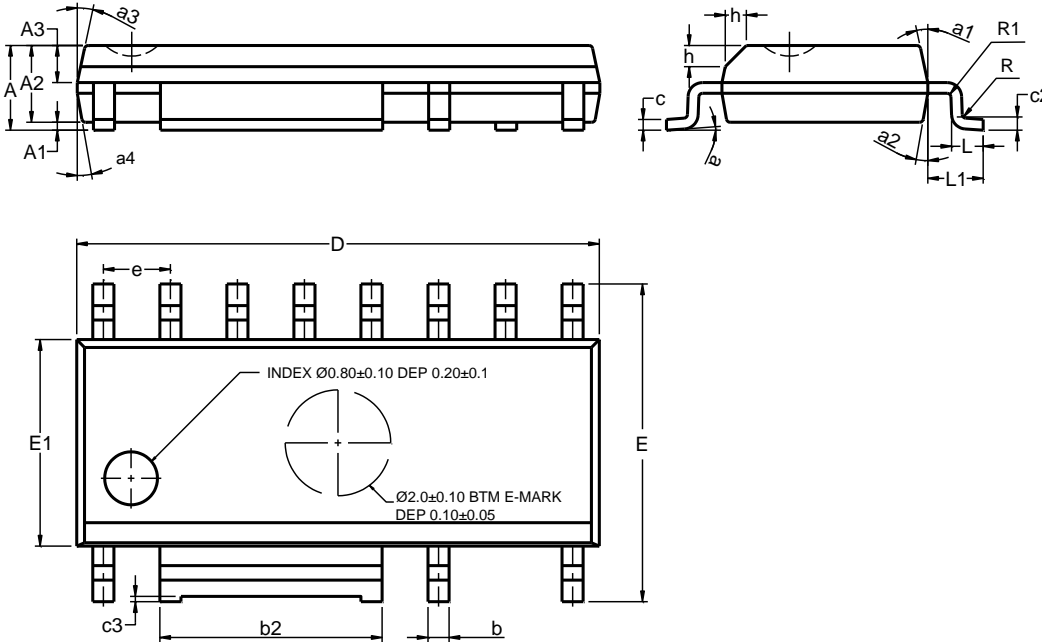


Package Outline Dimensions

HSOP-16 (Type SM)

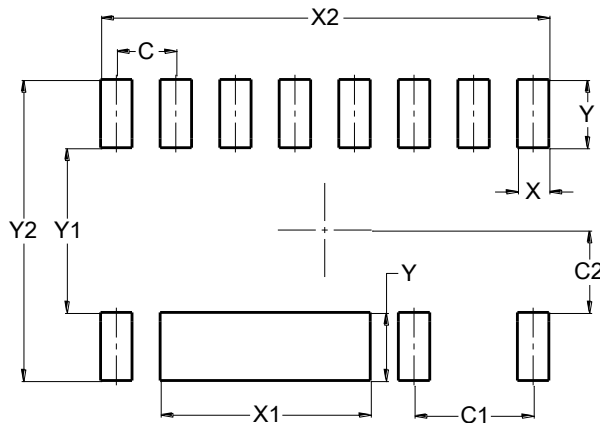


HSOP-16 (Type SM)			
Dim	Min	Max	Typ
A	1.35	1.75	1.60
A1	0.10	0.25	0.15
A2	1.25	1.65	1.45
A3	0.55	0.75	0.65
b	0.36	0.51	--
b2	4.17	4.32	--
c	0.17	0.25	--
c2	0.25BSC		
c3	0.00	0.15	--
D	9.80	10.00	9.90
E	5.80	6.20	6.00
E1	3.80	4.00	3.90
e	1.27BSC		
h	0.30	0.50	0.40
L	0.45	0.80	0.60
L1	1.04REF		
R	0.07	--	--
R1	0.07	--	--
a	0°	8°	--
a1	10°	14°	12°
a2	8°	12°	10°
a3	10°	14°	12°
a4	8°	12°	10°

All Dimensions in mm

Suggested Pad Layout

HSOP-16 (Type SM)



Dimensions	Value (in mm)
C	1.270
C1	2.540
C2	1.750
X	0.670
X1	4.480
X2	9.560
Y	1.450
Y1	3.500
Y2	6.400

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.